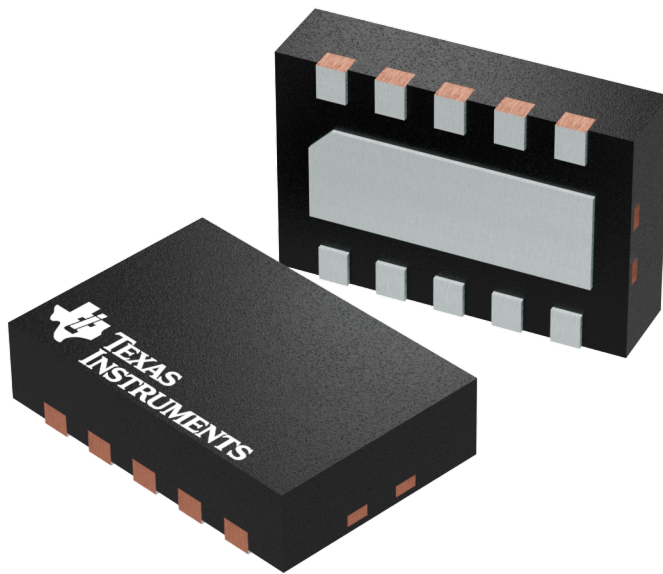


## GENERIC PACKAGE VIEW

DQC 10

WSO - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4209674/B

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